

Key Features

- Operating Frequency: 8.50-9.60 GHz
- Saturated Output Power (Psat): ≥ 50 dBm
- Power Gain(Gp): ≥ 8 dB
- Work Efficiency (η): ≥ 36%
- Port Matching: Zin/Zout = 50 Ω



Product Description

The MCNI8596-P50 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 8.50-9.60GHz.

This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	Vgs	-5	V
Storage Temperature	Tstg	-65 to +150	°C
Channel Temperature	Tch	150	°C

*Not recommended to work under these conditions.

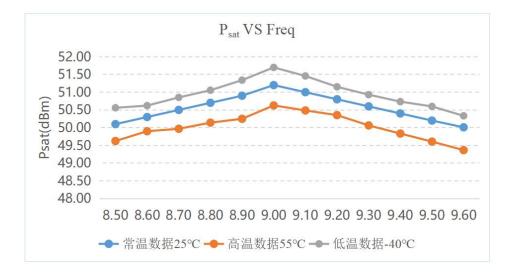
Microwave Electrical Characteristics

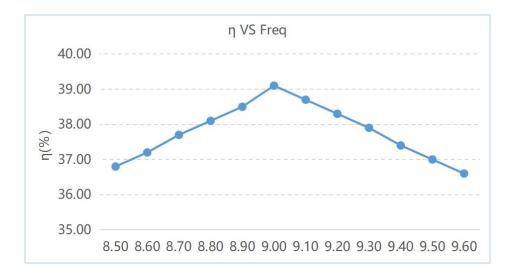
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	ldsr	VDS:28V Pulse T=1ms,Duty=10%	-	9.9	-	A
Saturated Output Power	Psat		50	-	-	dBm
Power Gain	Gp		8	-	-	dB
Work Efficiency	η	Pin: 42dBm	36	-	-	%
Gain Flatness	ΔG	Freq: 8.5~9.6GHZ	-0.8	-	0.8	dB

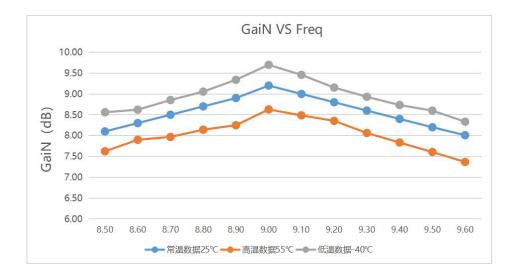


MCNI8596-P50 X-Band Internally Matched GaN Device

Typical Curves



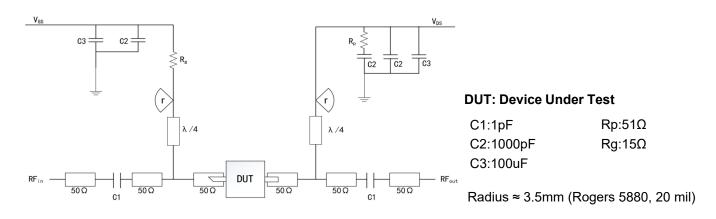






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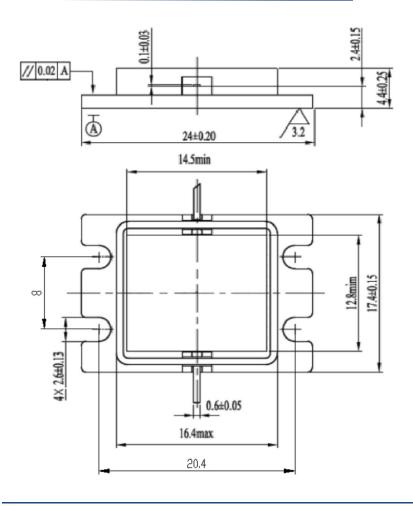
Recommended Application Circuit



ESD Level

ESD	Class III	2000V
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Overall Dimensions



Using Notes:

• During transportation and storage, ensure proper drying.

• During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.

• When powering on, apply gate voltage first, then apply leakage voltage.